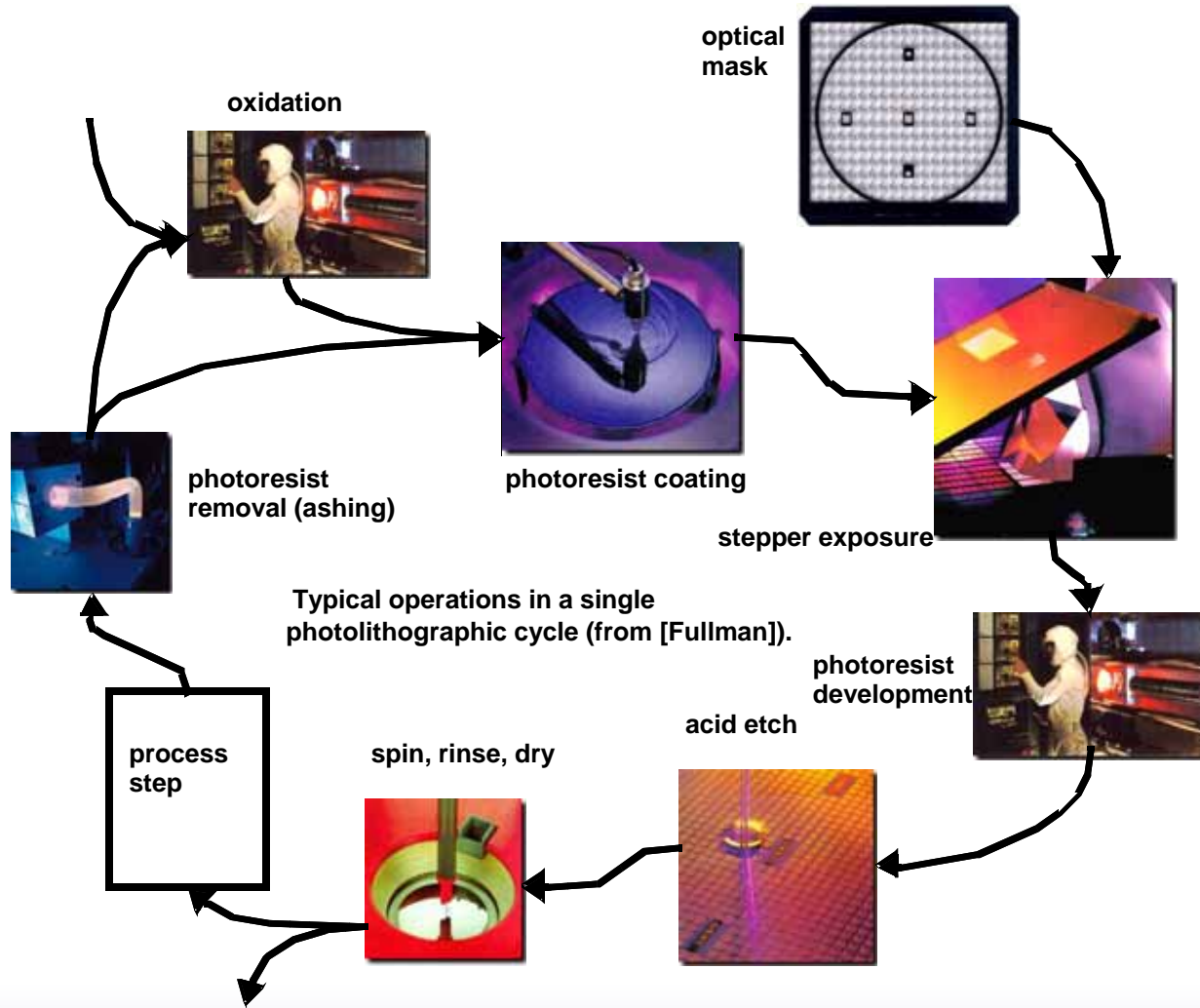
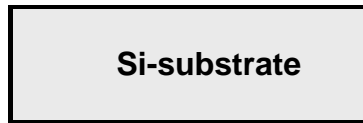


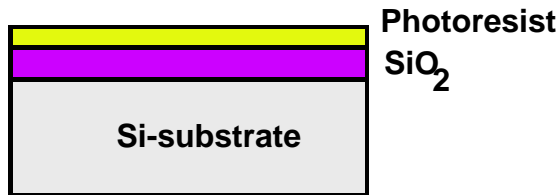
# Photo-Lithographic Process



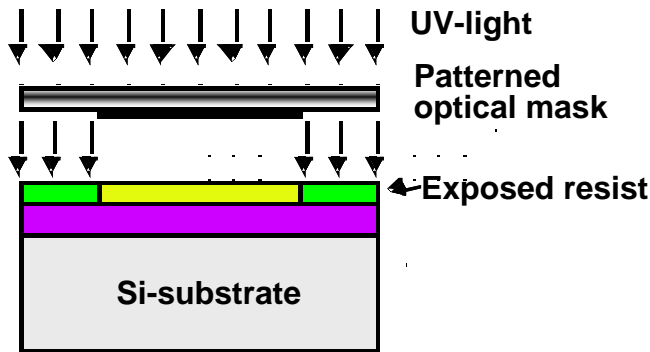
# Patterning of SiO<sub>2</sub>



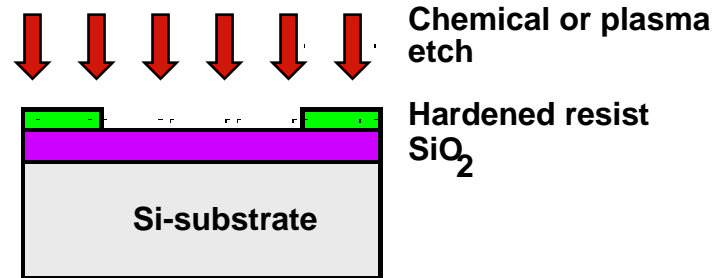
(a) Silicon base material



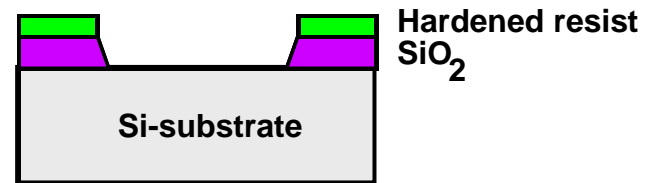
(b) After oxidation and deposition of negative photoresist



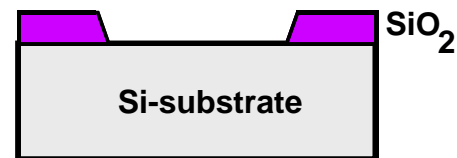
(c) Stepper exposure



(d) After development and etching of resist, chemical or plasma etch of SiO<sub>2</sub>



(e) After etching



(f) Final result after removal of resist